PCN Number:	20171108001	PCN Date:	November 28, 2017
Title:	Datasheet for WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD		
Customer Contact:	PCN Manager	Dept:	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD

SWRS152L – JULY 2013 – REVISED DECEMBER 2015

Changes from Revision K (November 2014) to Revision L — Page

The datasheet number will be changing.

Device Family	Change From:	Change To:
WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD	SWRS152M	SWRS152L

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/WL1801MOD

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

WL1801MODGBMOCR	WL1801MODGBMOCT	WL1805MODGBMOCR	WL1805MODGBMOCT
WL1831MODGBMOCR	WL1831MODGBMOCT	WL1835MODGBMOCR	WL1835MODGBMOCT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com